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- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- I_{off} Feature Supports Partial-Power-Down Mode Operation
- Supports 5-V V_{CC} Operation
- Package Options Include Plastic Small-Outline Transistor (DBV, DCK) Packages

description

This single 2-input positive-OR gate is designed for 1.65-V to 5.5-V V_{CC} operation.

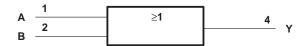
The SN74LVC1G32 performs the Boolean function Y = A + B or $Y = \overline{A \bullet B}$ in positive logic.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The SN74LVC1G32 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE								
INPUTS		OUTPUT						
Α	В	Y						
н х		Н						
Х	Н	н						
L	L	L						

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





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DBV OR DCK PACKAGE (TOP VIEW) A 1 5 V_{CC} B 2 GND 3 4 Y

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input voltage range, V_I (see Note 1) Output voltage range, V_O (see Notes 1 and 2)0. Input clamp current, I_{IK} ($V_I < 0$) Output clamp current, I_{OK} ($V_O < 0$) Continuous output current, I_O Continuous current through V_{CC} or GND Package thermal impedance, θ_{JA} (see Note 3): DBV package DCK package	$\begin{array}{c} \dots -0.5 \ V \ to \ 6.5 \ V \\ 5 \ V \ to \ V_{CC} + 0.5 \ V \\ \dots & -50 \ mA \\ \dots & -50 \ mA \\ \dots & \pm 50 \ mA \\ \dots & \pm 100 \ mA \\ \dots & 347^{\circ}C/W \\ \dots & 389^{\circ}C/W \end{array}$
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The value of V_{CC} is provided in the recommended operating conditions table.

3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
14	Currente unelte en	Operating	1.65	5.5	M
VCC	Supply voltage	Data retention only	1.5		V
	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		
Mar .		V_{CC} = 2.3 V to 2.7 V	1.7		V
VIH		$V_{CC} = 3 V \text{ to } 3.6 V$	2		v
		$V_{CC} = 4.5 \text{ V} \text{ to } 5.5 \text{ V}$			
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
V		V _{CC} = 2.3 V to 2.7 V		0.7	V
VIL	Low-level input voltage	V _{CC} = 3 V to 3.6 V		0.8	
		V _{CC} = 4.5 V to 5.5 V		$0.3 \times V_{CC}$	
VI	Input voltage	•	0	5.5	V
VO	Output voltage		0	V _{CC}	V
		V _{CC} = 1.65 V		-4	
	High-level output current	V _{CC} = 2.3 V		-8	mA
ЮН				-16	
		V _{CC} = 3 V		-24	
		V _{CC} = 4.5 V		-32	
		V _{CC} = 1.65 V		4	
	Low-level output current	V _{CC} = 2.3 V		8	
IOL				16	mA
		$V_{CC} = 3 V$		24	
		V _{CC} = 4.5 V			
	Input transition rise or fall rate	V_{CC} = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V		20	
$\Delta t/\Delta v$		V _{CC} = 3.3 V ± 0.3 V		10	ns/V
		V _{CC} = 5 V ± 0.5 V		5	
TA	Operating free-air temperature	-	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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PAF	RAMETER	TEST CONDITIONS	Vcc	MIN	TYPT	MAX	UNIT		
		I _{OH} = -100 μA	1.65 V to 5.5 V	V _{CC} -0.1					
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2					
		I _{OH} = -8 mA	2.3 V	1.9					
Vон		I _{OH} = -16 mA		2.4			V		
		I _{OH} = -24 mA	3 V	2.3					
		I _{OH} = -32 mA	4.5 V	3.8					
		I _{OL} = 100 μA	1.65 V to 5.5 V			0.1			
	-	I _{OL} = 4 mA	1.65 V			0.45			
N		I _{OL} = 8 mA	2.3 V			0.3			
VOL		I _{OL} = 16 mA				0.4	V		
		I _{OL} = 24 mA	3 V			0.55			
		I _{OL} = 32 mA	4.5 V			0.55			
Ц	A or B inputs	V _I = 5.5 V or GND	0 to 5.5 V			±5	μA		
loff		$V_{I} \text{ or } V_{O} = 5.5 \text{ V}$	0			±10	μA		
ICC		$V_{I} = 5.5 V \text{ or GND}, \qquad I_{O} = 0$	1.65 V to 5.5 V			10	μA		
∆ICC		One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	3 V to 5.5 V			500	μA		
Ci		V _I = V _{CC} or GND	3.3 V				pF		

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at V_{CC} = 3.3 V, $T_A = 25^{\circ}C$.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 4)

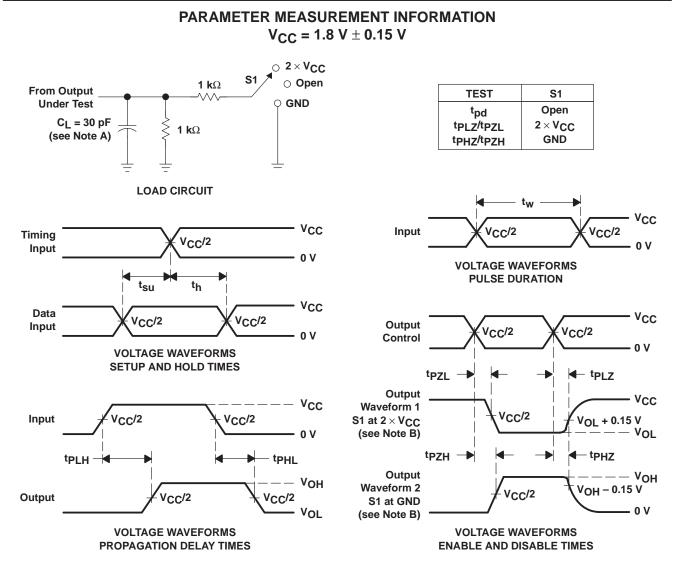
	PARAMETER	FROM TO (INPUT) (OUTPUT)	-	V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = ± 0.		= V _{CC} ± 0.		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	^t pd	A or B	Y									ns

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	V _{CC} = 5 V	UNIT	
FARAMETER		TEST CONDITIONS	TYP	TYP	TYP	TYP		
Cpd	Power dissipation capacitance	f = 10 MHz					pF	



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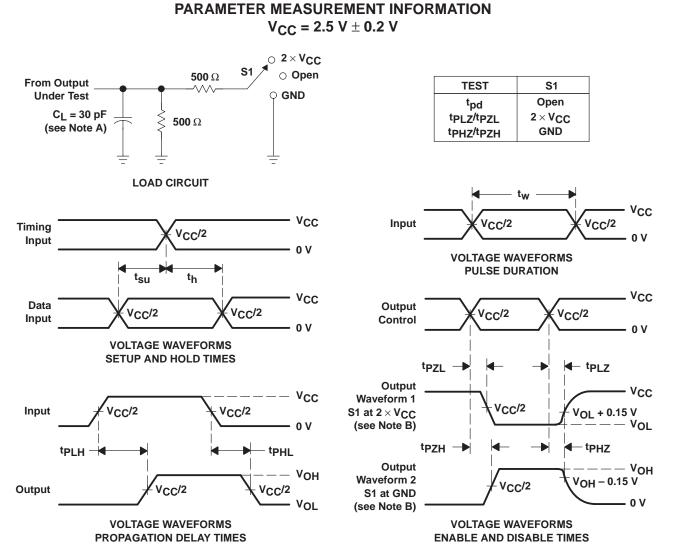


- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Q = 50 Ω, t_f ≤ 2 ns, t_f ≤ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms



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- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_f ≤ 2 ns, t_f ≤ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - D. The outputs are measured one at a time with one training the period of the second sector.
 - E. tpLZ and tpHZ are the same as t_{dis}.F. tpZL and tpZH are the same as t_{en}.
 - G. tp[H and tpH] are the same as t_{pd} .

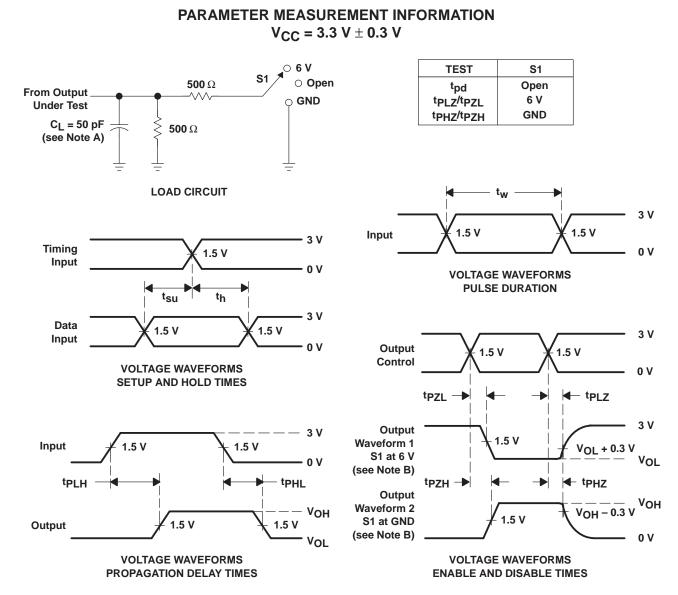
Figure 2. Load Circuit and Voltage Waveforms

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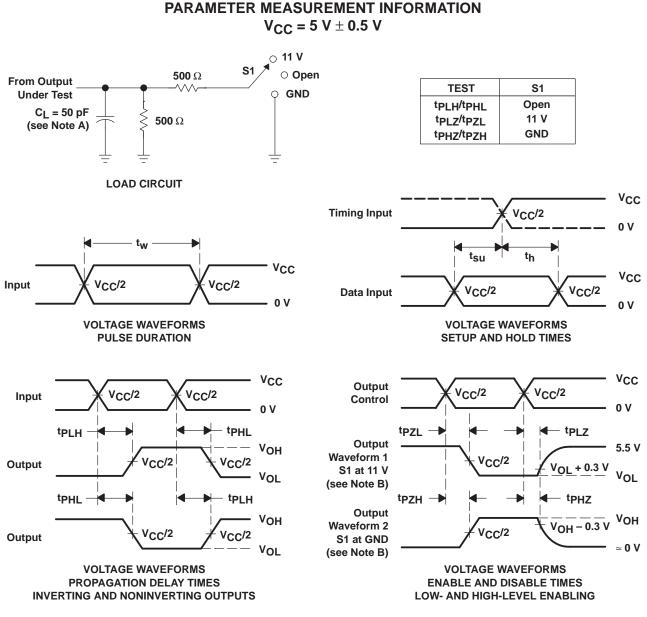
NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_Q = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. tpLH and tpHL are the same as t_{pd} .

Figure 3. Load Circuit and Voltage Waveforms



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NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Q = 50 Ω, t_f ≤ 2.5 ns. t_f ≤ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. tp $_{\rm H}$ and tp $_{\rm H}$ are the same as t_{pd}.

Figure 4. Load Circuit and Voltage Waveforms



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